

**ABSOLUTE MAXIMUM RATINGS**

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum average forward current	$I_{F(AV)}$	$T_C = 105\text{ }^{\circ}\text{C}$, 180° conduction half sine wave	10	A
Maximum peak one cycle non-repetitive surge current	I_{FSM}	10 ms sine pulse, rated V_{RRM} applied	135	
		10 ms sine pulse, no voltage reapplied	160	
Maximum I^2t for fusing	I^2t	10 ms sine pulse, rated V_{RRM} applied	91	A^2s
		10 ms sine pulse, no voltage reapplied	130	
Maximum $I^2\sqrt{t}$ for fusing	$I^2\sqrt{t}$	$t = 0.1\text{ ms to }10\text{ ms}$, no voltage reapplied	1290	$\text{A}^2\sqrt{\text{s}}$

ELECTRICAL SPECIFICATIONS

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum forward voltage drop	V_{FM}	10 A, $T_J = 25\text{ }^{\circ}\text{C}$	1.1	V
Forward slope resistance	r_t	$T_J = 150\text{ }^{\circ}\text{C}$	20	$\text{m}\Omega$
Threshold voltage	$V_{F(TO)}$		0.82	V
Maximum reverse leakage current	I_{RM}	$T_J = 25\text{ }^{\circ}\text{C}$	0.05	mA
		$T_J = 150\text{ }^{\circ}\text{C}$	0.50	

THERMAL - MECHANICAL SPECIFICATIONS

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum junction and storage temperature range	T_J, T_{Stg}		-40 to +150	$^{\circ}\text{C}$
Maximum thermal resistance, junction to case	R_{thJC}	DC operation	2.5	$^{\circ}\text{C/W}$
Maximum thermal resistance, junction to ambient (PCB mount)	$R_{thJA}^{(1)}$		62	
Soldering temperature	T_S		260	$^{\circ}\text{C}$
Approximate weight			2	g
			0.07	oz.
Marking device		Case style TO-263AB (D ² PAK)	10ETS08S	
			10ETS10S	
			10ETS12S	

Note

- (1) When mounted on 1" square (650 mm²) PCB of FR-4 or G-10 material 4 oz. (140 μm) copper 40 $^{\circ}\text{C/W}$
For recommended footprint and soldering techniques refer to application note #AN-994

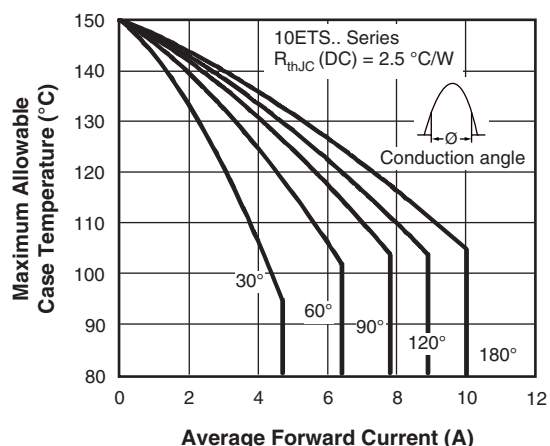


Fig. 1 - Current Rating Characteristics

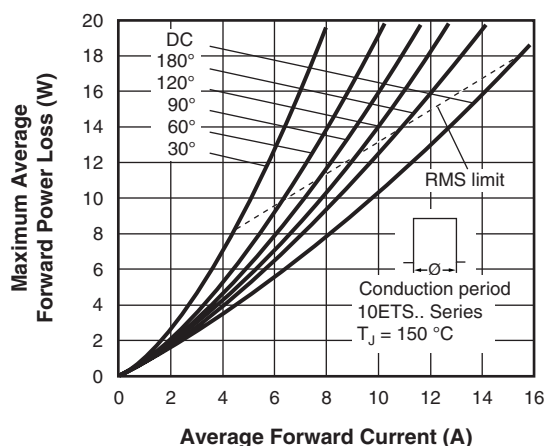


Fig. 4 - Forward Power Loss Characteristics

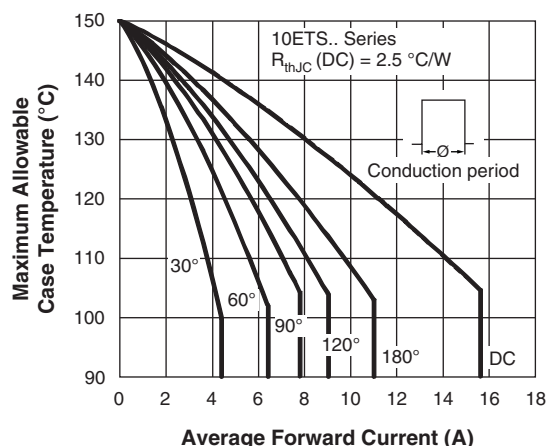


Fig. 2 - Current Rating Characteristics

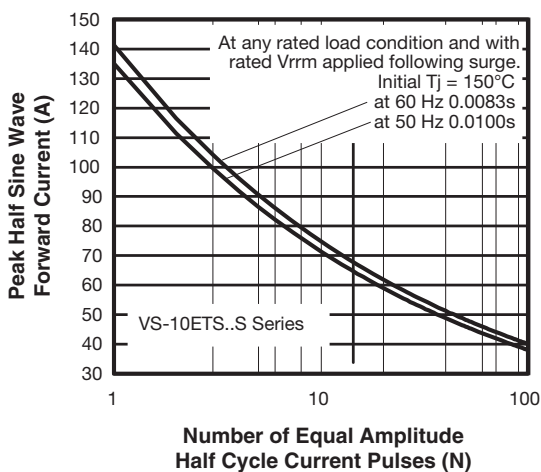


Fig. 5 - Maximum Non-Repetitive Surge Current

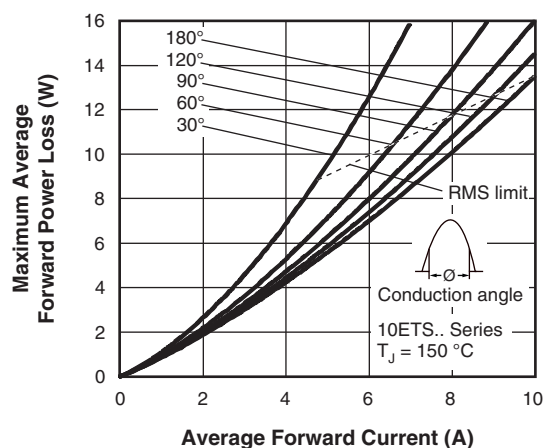


Fig. 3 - Forward Power Loss Characteristics

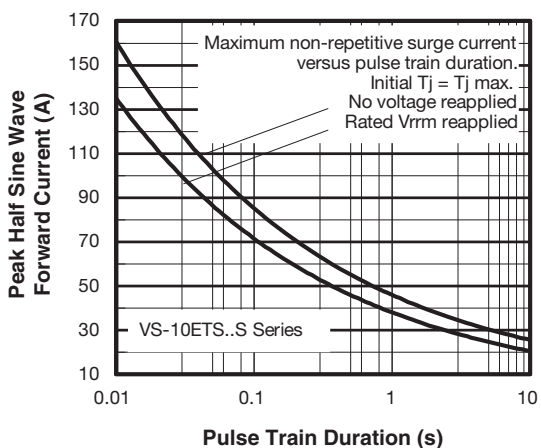


Fig. 6 - Maximum Non-Repetitive Surge Current

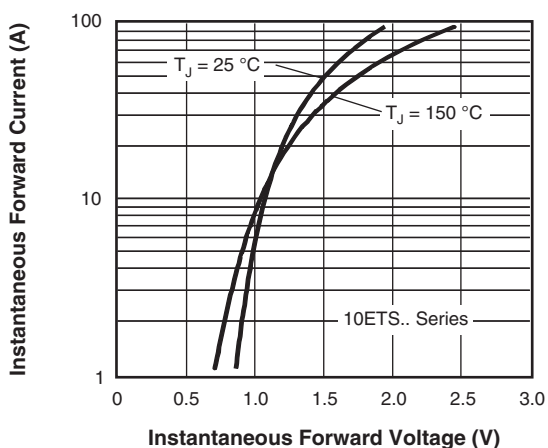
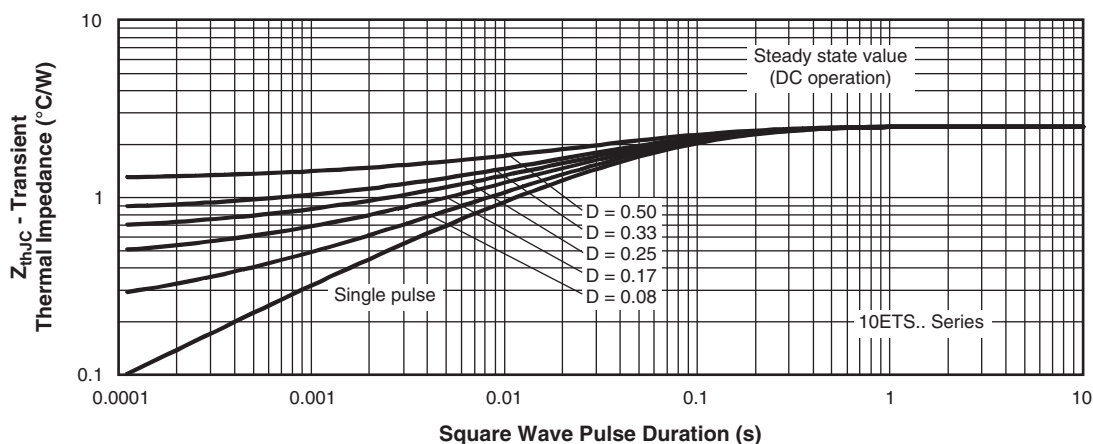


Fig. 7 - Forward Voltage Drop Characteristics


Fig. 8 - Thermal Impedance Z_{thJC} Characteristics

**ORDERING INFORMATION TABLE**

Device code	VS-	10	E	T	S	12	S	TRL	PbF
	1	2	3	4	5	6	7	8	9

- 1** - Vishay Semiconductors product
- 2** - Current rating (10 = 10 A)
- 3** - Circuit configuration:
E = single diode
- 4** - Package:
T = TO-220AC
- 5** - Type of silicon:
S = standard recovery rectifier
- 6** - Voltage code x 100 = V_{RRM}
- 7** - S = TO-220 D²PAK (SMD-220) version
- 8** -
 - None = tube
 - TRL = tape and reel (left oriented)
 - TRR = tape and reel (right oriented)
- 9** - PbF = Lead (Pb)-free

08 = 800 V
10 = 1000 V
12 = 1200 V

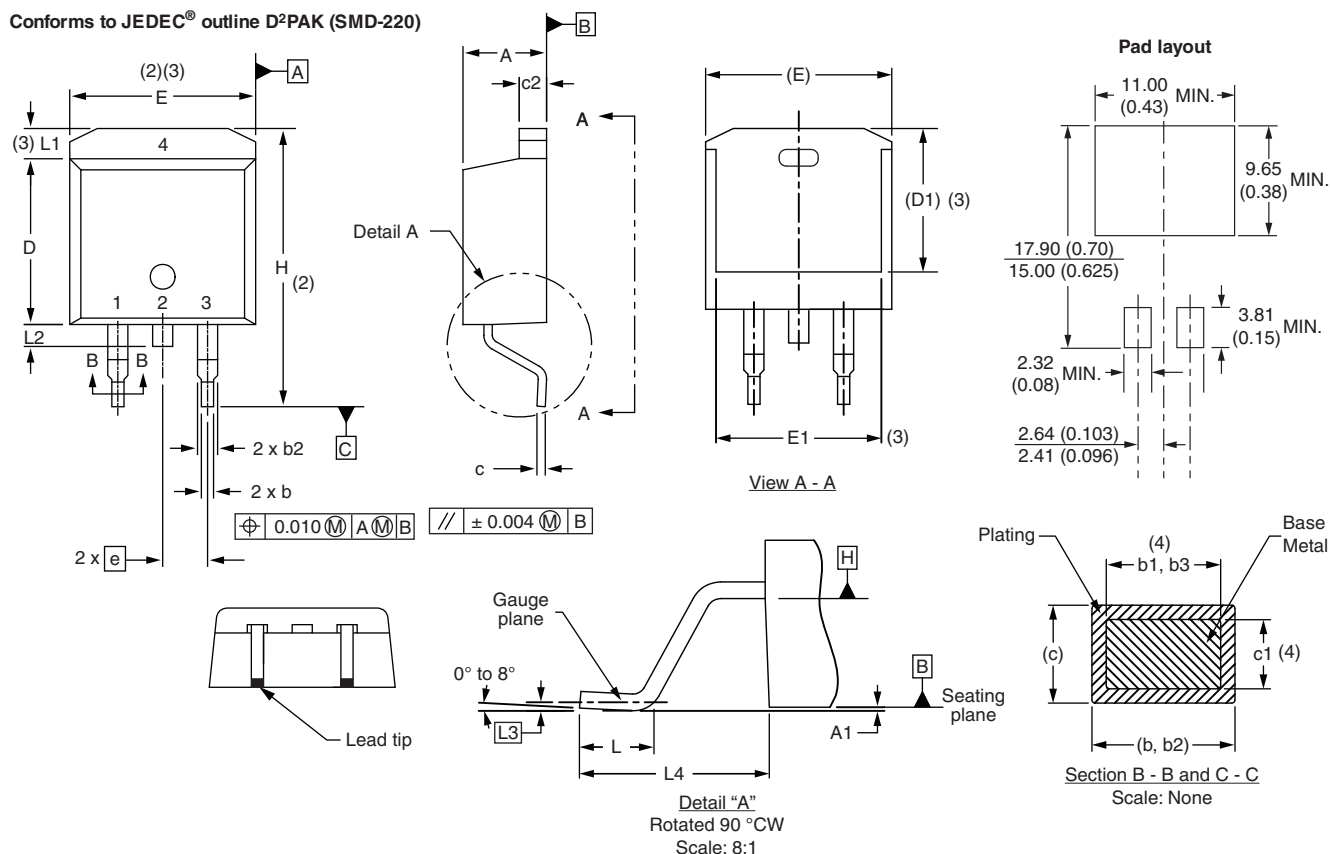
ORDERING INFORMATION (Example)			
PREFERRED P/N	QUANTITY PER TUBE	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION
VS-10ETS08SPbF	50	1000	Antistatic plastic tube
VS-10ETS08STRRPbF	800	800	13" diameter reel
VS-10ETS08STRLPbF	800	800	13" diameter reel
VS-10ETS10SPbF	50	1000	Antistatic plastic tube
VS-10ETS10STRRPbF	800	800	13" diameter reel
VS-10ETS10STRLPbF	800	800	13" diameter reel
VS-10ETS12SPbF	50	1000	Antistatic plastic tube
VS-10ETS12STRRPbF	800	800	13" diameter reel
VS-10ETS12STRLPbF	800	800	13" diameter reel
VS-10ETS08SPbF	50	1000	Antistatic plastic tube

LINKS TO RELATED DOCUMENTS	
Dimensions	www.vishay.com/doc?95046
Part marking information	www.vishay.com/doc?95054
Packaging information	www.vishay.com/doc?95032

D²PAK

DIMENSIONS in millimeters and inches

Conforms to JEDEC® outline D²PAK (SMD-220)



SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
A	4.06	4.83	0.160	0.190	
A1	0.00	0.254	0.000	0.010	
b	0.51	0.99	0.020	0.039	
b1	0.51	0.89	0.020	0.035	4
b2	1.14	1.78	0.045	0.070	
b3	1.14	1.73	0.045	0.068	4
c	0.38	0.74	0.015	0.029	
c1	0.38	0.58	0.015	0.023	4
c2	1.14	1.65	0.045	0.065	
D	8.51	9.65	0.335	0.380	2

SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
D1	6.86	8.00	0.270	0.315	3
E	9.65	10.67	0.380	0.420	2, 3
E1	7.90	8.80	0.311	0.346	3
e	2.54 BSC		0.100 BSC		
H	14.61	15.88	0.575	0.625	
L	1.78	2.79	0.070	0.110	
L1	-	1.65	-	0.066	3
L2	1.27	1.78	0.050	0.070	
L3	0.25 BSC		0.010 BSC		
L4	4.78	5.28	0.188	0.208	

Notes

- Dimensioning and tolerancing per ASME Y14.5 M-1994
- Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- Thermal pad contour optional within dimension E, L1, D1 and E1
- Dimension b1 and c1 apply to base metal only
- Datum A and B to be determined at datum plane H
- Controlling dimension: inch
- Outline conforms to JEDEC® outline TO-263AB



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